

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

AMENDMENTS TO THE CLAIMS(IN REVISED FORMAT COMPLIANT WITH THE PROPOSEDREVISION TO 37 CFR 1.121)

1. (CURRENTLY AMENDED) An apparatus comprising:

B1 5 a circuit configured to generate a plurality of identification (ID) codes in response to a logical combination of (i) one or more voltage levels on one or more inputs, (ii) a state of one or more bond options and (iii) a state of one or more metal options; and

10 a package comprising one or more pins dedicated to providing said one or more voltage levels to respective ones of said one or more inputs, ~~wherein said one or more voltage levels determine which of said plurality of identification codes is generated by said circuit.~~

2. (PREVIOUSLY AMENDED) The apparatus according to claim 1, wherein said ID codes comprise a silicon ID of an electronic part.

3. (CURRENTLY AMENDED) The apparatus according to claim 1, wherein said circuit is further configured to generate said plurality of ID codes having a number of bits less than a total number of said in response to one or more options selected from the

5 ~~group consisting of~~ metal options, bond options, and ~~hard-coded~~
options pins.

4. (CURRENTLY AMENDED) The apparatus according to claim 1, wherein said one or more pins are connected connectable to either a voltage supply power or a voltage supply ground according to markings on said package.

B' 5. (PREVIOUSLY AMENDED) The apparatus according to claim 1, wherein each of said plurality of ID codes comprises a part number for said apparatus.

6. (PREVIOUSLY AMENDED) The apparatus according to claim 5, wherein said part number is combined with other identification codes.

7. (PREVIOUSLY AMENDED) The apparatus according to claim 6, wherein said other ID codes comprise one or more codes selected from the group consisting of a version number and a manufacturing number.

8. (PREVIOUSLY AMENDED) The apparatus according to claim 1, wherein said ID code is captured in a register in response to an identification request.

9. (ORIGINAL) The apparatus according to claim 8, wherein said register comprises a JTAG ID code register.

10. (ORIGINAL) The apparatus according to claim 1, wherein said apparatus comprises a programmable logic device (PLD).

11. (CURRENTLY AMENDED) The apparatus according to claim 1, wherein said metal options are set to indicate an operating voltage of said apparatus.

12. (CURRENTLY AMENDED) The apparatus according to claim 1, wherein said bond options are set based on a style of said package of said apparatus.

13. (CURRENTLY AMENDED) The apparatus according to claim 1, wherein said one or more pins are labeled as either a first or a second supply voltage.

14. (CURRENTLY AMENDED) The apparatus according to claim 13, wherein said one or more pins are labeled as either said first or said second supply voltage based on characteristics of said apparatus.

15. (PREVIOUSLY AMENDED) The apparatus according to claim 14, wherein said characteristics comprise one or more characteristics selected from the group consisting of volatility, price, package, metal options, operating voltage, internal structure, part category and density.

16. (CURRENTLY AMENDED) A method of providing a plurality of identification codes for a single die and package combination comprising the steps of:

(A) dedicating (i) one or more pins of said package,
(ii) one or more bond options and (iii) one or more metal options
to ~~selecting any of~~ generating a plurality of identification codes;

(B) generating said plurality of identification codes in response to a logical combination of (i) voltage levels on said one or more pins, (ii) a state of said one or more bond options and (iii) a state of said one or more metal options; and

(C) providing an indication of said voltage levels to be applied to each of said one or more pins.

17. (CURRENTLY AMENDED) The method according to claim 16, wherein the step (B) further comprises the steps of:

determining said voltage levels on said one or more pins;

5 determining a said state of said one or more metal options;

determining a said state of said one or more bond options; and

10 ~~generating said identification code in response to a logical combination of~~ logically combining a result of each determining step.

B' 18. (CURRENTLY AMENDED) The method according to claim 16, further comprising the step of:

presenting a ~~selected~~ generated identification code in response to an identification request.

19. (ORIGINAL) The method according to claim 18, wherein said identification request comprises a JTAG ID code instruction.

20. (CURRENTLY AMENDED) An apparatus comprising:

5 means for generating a plurality of identification codes in response to a logical combination of (i) one or more voltage levels asserted at one or more inputs, (ii) a state of one or more bond options and (iii) a state of one or more metal options; and

means for packaging said generating means comprising one or more pins dedicated to providing said one or more voltage levels

to respective ones of said one or more inputs, ~~wherein said one or~~
~~more voltage levels determine which of said plurality of~~
10 ~~identification codes is generated by said circuit.~~

b1
21. (PREVIOUSLY NEW) The apparatus according to claim
1, wherein said apparatus can present any of said plurality of
identification codes after packaging.

22. (PREVIOUSLY NEW) The apparatus according to claim
1, wherein said apparatus changes identification code in response
to a change in said one or more voltage levels applied to said one
or more pins.

23. (PREVIOUSLY NEW) The apparatus according to claim 1,
wherein said package further comprises one or more pins dedicated
to a test access port, at least one voltage supply pin and at least
one ground pin.

24. (PREVIOUSLY NEW) The method according to claim 16,
further comprising:

5 marking voltage level indications on said package after
assembly to select a particular one of said plurality of
identification codes for said die and package combination.

B¹ 25. (PREVIOUSLY NEW) The method according to claim 16,
further comprising:

changing voltage level indications provided to select
different identification codes.
